

Product Information

FLAST S

Water-soluble soldering flux

This water soluble soldering flux is superior to soldering for stainless, brass, copper and nickel. It is able to be soldered at about 250°C. When the soldering temperature become more than 350°C, you can not be soldering, because the activator is dissolved at 350°C. Please use this flux under 300°C.

Table . Characteristics

Items		Characteristics	Test method
Appearance and the tone of color		Colorless and Clear Liquid	—
Viscosity of flux (mPa·s)		41.4	MALCOM PCU-2 10rpm, 3minutes
pH of flux		2.0	pH meter
Specific gravity of flux		1.550±0.020	H ₂ O=1, at 20°C
Halide content (%)		0	JIS Z 3197 8.1.4.2.1
Copper plate corrosion test		Not passed	JIS Z 3197 8.4.1
Spreading factor (%)	Copper	92	JIS Z 3197 8.3.1.1 at 250°C
	Brass	92	
	Nickle	90	
	Stainless	90	
	Steel	91	
Reducer solvent		Water	—
Rinsing solution		Hot water	—
Remarks		JIS Z 3197 Testing method for soldering fluxes	